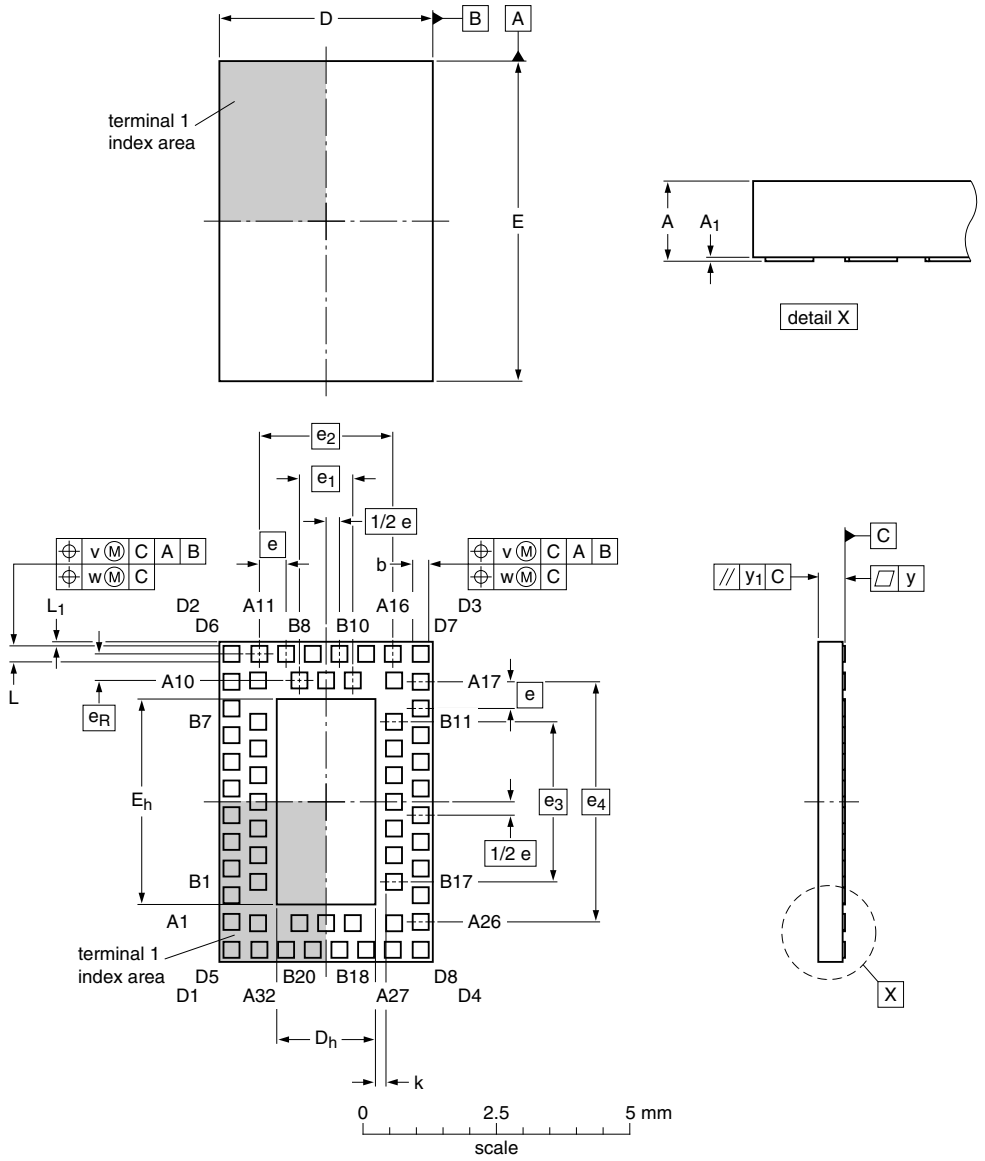
HXQFN60U: plastic thermal enhanced extremely thin quad flat package; no leads; 60 terminals; UTLP based; body 4 x 6 x 0.5 mm **SOT1134-1**



Dimensions

Unit		A	A_1	b	D	D_h	E	E_h	e	e_1	e_2	e_3	e_4	eR	k	L	L_1	v	w	y	y_1
	max	0.50	0.05	0.35	4.1	1.90	6.1	3.90							0.25	0.35	0.125				
mm	nom	0.48	0.02	0.30	4.0	1.85	6.0	3.85	0.5	1	2.5	3	4.5	0.5	0.20	0.30	0.075	0.07	0.05	0.08	0.1
	min	0.46	0.00	0.25	3.9	1.80	5.9	3.80							0.15	0.25	0.025				

sot1134-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1134-1	- - -	- - -	- - -			~~08-12-17~~ 09-01-22

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